

Dual N-Channel Power MOSFET

20V, 5.8A, 25mΩ

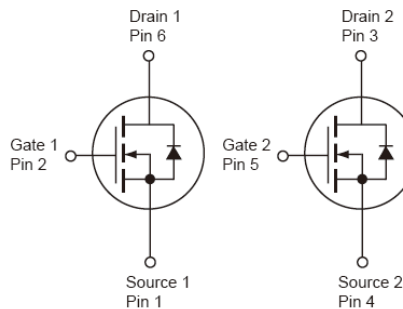
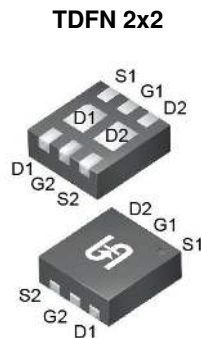
Features

- Halogen-Free according to IEC 61249-2-21
- Suited for 1.8V drive applications
- Low profile package
- RoHS Compliant

APPLICATION

- Battery Pack
- Load Switch

KEY PERFORMANCE PARAMETERS		
PARAMETER	VALUE	UNIT
V_{DS}	20	V
$R_{DS(on)}$ (max)	$V_{GS} = 4.5V$	25
	$V_{GS} = 2.5V$	35
	$V_{GS} = 1.8V$	55
Q_g	7.7	nC



Notes: Moisture sensitivity level: level 3. Per J-STD-020

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 10	V
Continuous Drain Current ^(Note 1)	I_D	$T_C = 25^\circ C$	5.8
		$T_C = 100^\circ C$	3.48
Pulsed Drain Current ^(Note 2)	I_{DM}	23.2	A
Total Power Dissipation @ $T_C = 25^\circ C$	P_{DTOT}	0.62	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to +150	$^\circ C$

THERMAL PERFORMANCE			
PARAMETER	SYMBOL	LIMIT	UNIT
Junction to Ambient Thermal Resistance	$R_{\theta JA}$	200	$^\circ C/W$

Notes: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. $R_{\theta JA}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design. $R_{\theta JA}$ shown below for single device operation on FR-4 PCB in still air.

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static (Note 3)						
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	BV_{DSS}	20	--	--	V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	$V_{GS(TH)}$	0.4	0.6	0.8	V
Gate Body Leakage	$V_{GS} = \pm 10\text{V}, V_{DS} = 0\text{V}$	I_{GSS}	--	--	± 100	nA
Zero Gate Voltage Drain Current	$V_{DS} = 16\text{V}, V_{GS} = 0\text{V}$	I_{DSS}	--	--	1	μA
Drain-Source On-State Resistance	$V_{GS} = 4.5\text{V}, I_D = 4\text{A}$	$R_{DS(on)}$	--	20	25	m Ω
	$V_{GS} = 2.5\text{V}, I_D = 3\text{A}$		--	27	35	
	$V_{GS} = 1.8\text{V}, I_D = 2\text{A}$		--	39	55	
Forward Transconductance	$V_{DS} = 10\text{V}, I_D = 3\text{A}$	g_{fs}	--	6.5	--	S
Dynamic (Note 4)						
Total Gate Charge	$V_{DS} = 10\text{V}, I_D = 4\text{A},$ $V_{GS} = 4.5\text{V}$	Q_g	--	7.7	11	nC
Gate-Source Charge		Q_{gs}	--	0.9	1	
Gate-Drain Charge		Q_{gd}	--	2.4	5	
Input Capacitance	$V_{DS} = 10\text{V}, V_{GS} = 0\text{V},$ $f = 1.0\text{MHz}$	C_{iss}	--	535	775	pF
Output Capacitance		C_{oss}	--	60	85	
Reverse Transfer Capacitance		C_{rss}	--	34	50	
Switching (Note 5)						
Turn-On Delay Time	$V_{DD} = 10\text{V}, I_D = 1\text{A},$ $V_{GS} = 4.5\text{V}, R_G = 25\Omega$	$t_{d(on)}$	--	4.1	8	ns
Turn-On Rise Time		t_r	--	11.6	22	
Turn-Off Delay Time		$t_{d(off)}$	--	23.9	45	
Turn-Off Fall Time		t_f	--	7.6	14	
Source-Drain Diode (Note 3)						
Continuous Source Current		I_S	--	--	5.8	A
Used Source Current		I_{SM}	--	--	23.2	A
Forward On Voltage	$V_{GS} = 0\text{V}, I_S = 1\text{A}$	V_{SD}	--	--	1	V

Notes:

1. Current limited by package.
2. Pulse width limited by the maximum junction temperature.
3. Pulse test: $PW \leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
4. For DESIGN AID ONLY, not subject to production testing.
5. Switching time is essentially independent of operating temperature.

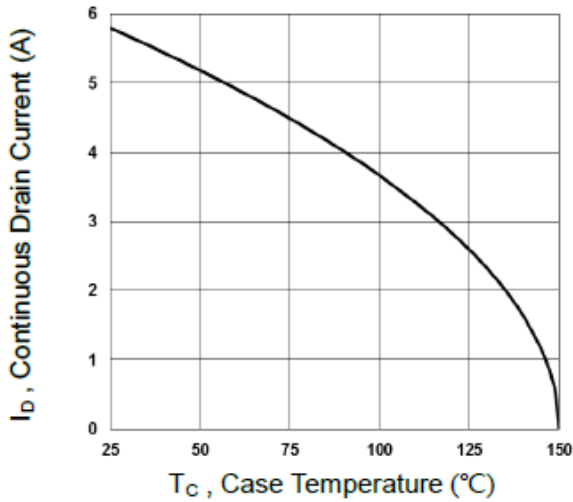
ORDERING INFORMATION

PART NO.	PACKAGE	PACKING
TSM250N02DCQ RFG	TDFN 2x2	3,000pcs / 7" Reel

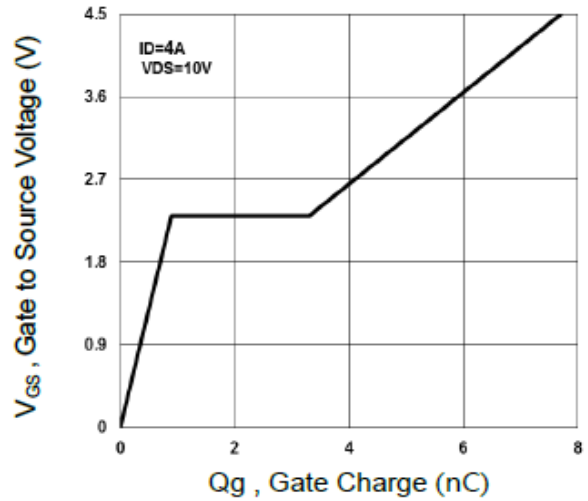
CHARACTERISTICS CURVES

($T_C = 25^\circ\text{C}$ unless otherwise noted)

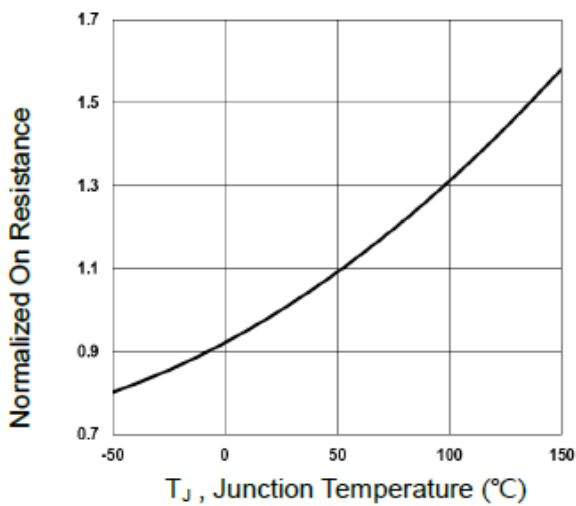
Continuous Drain Current vs. T_C



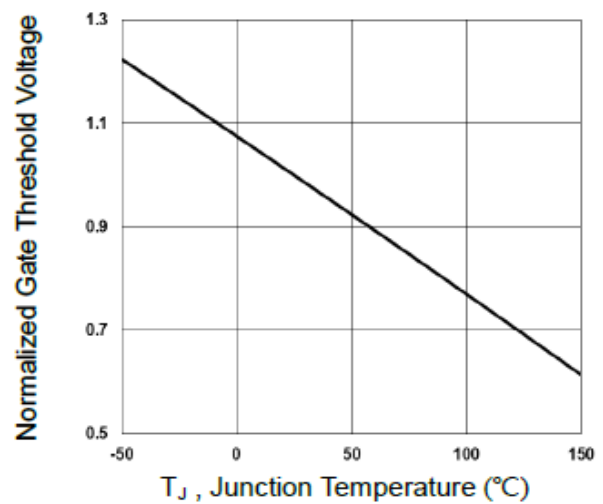
Gate Charge



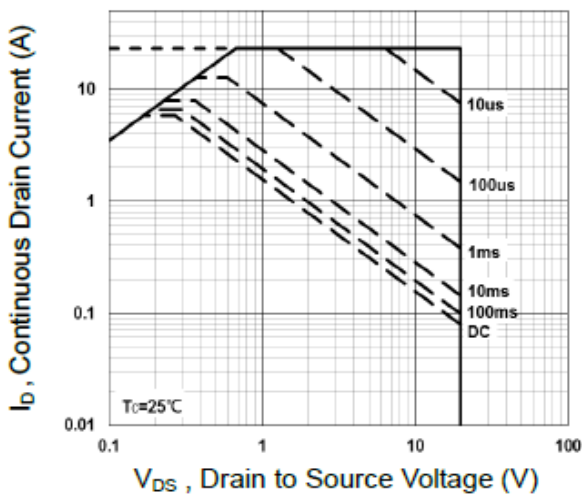
On-Resistance vs. Junction Temperature



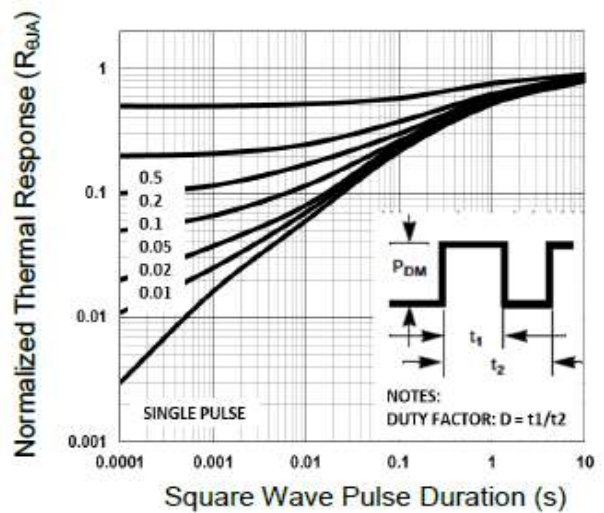
Threshold Voltage vs. Junction Temperature



Maximum Safe Operating Area

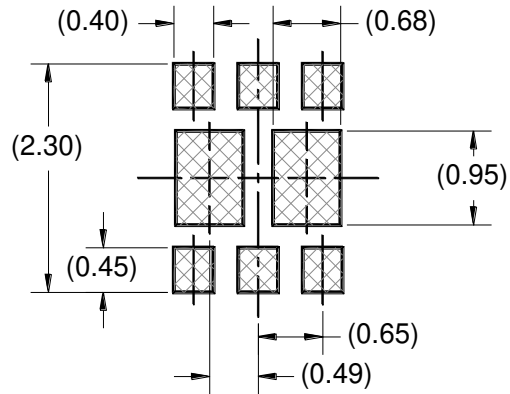
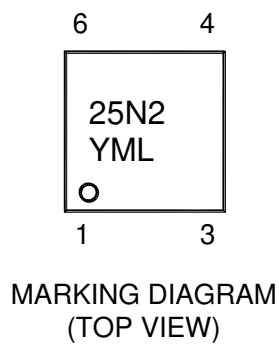
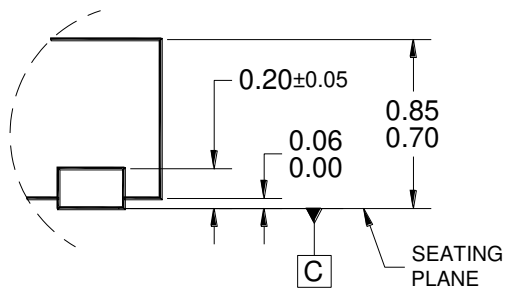
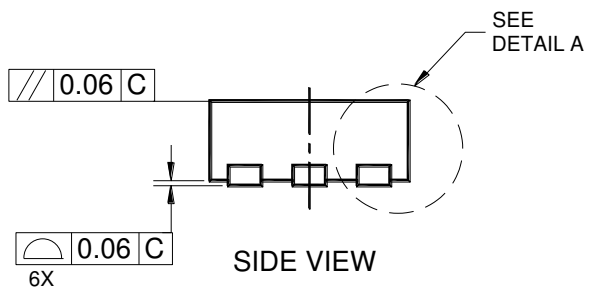
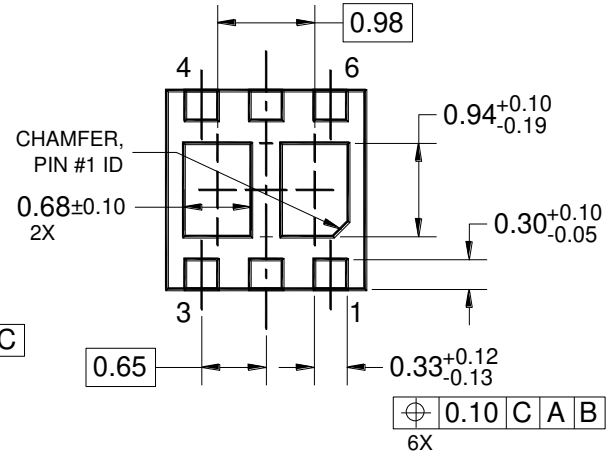
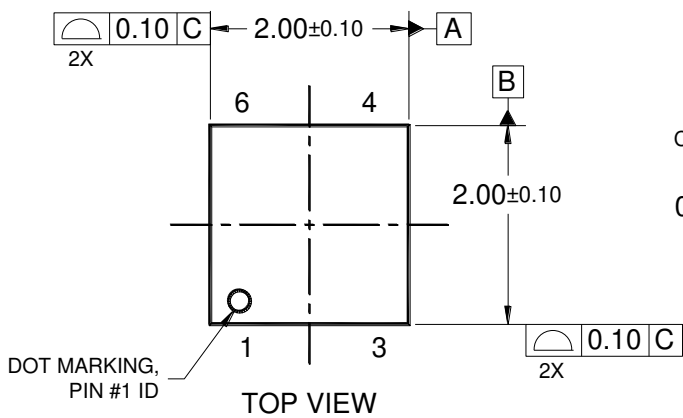


Normalized Thermal Transient Impedance Curve



PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

TDFN2x2



P/N = DEVICE CODE
 Y = YEAR CODE
 M = MONTH CODE FOR HALOGEN FREE PRODUCT
 O = JAN P = FEB Q = MAR R = APR
 S = MAY T = JUN U = JUL V = AUG
 W = SEP X = OCT Y = NOV Z = DEC
 L = LOT CODE (1~9, A~Z)

NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. SEATING PLANE IS DEFINED BY TERMINAL BOTTOM SURFACE ONLY.
4. DWG NO. REF: HQ2SD07-TDFN2X2D-003 REV A

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